

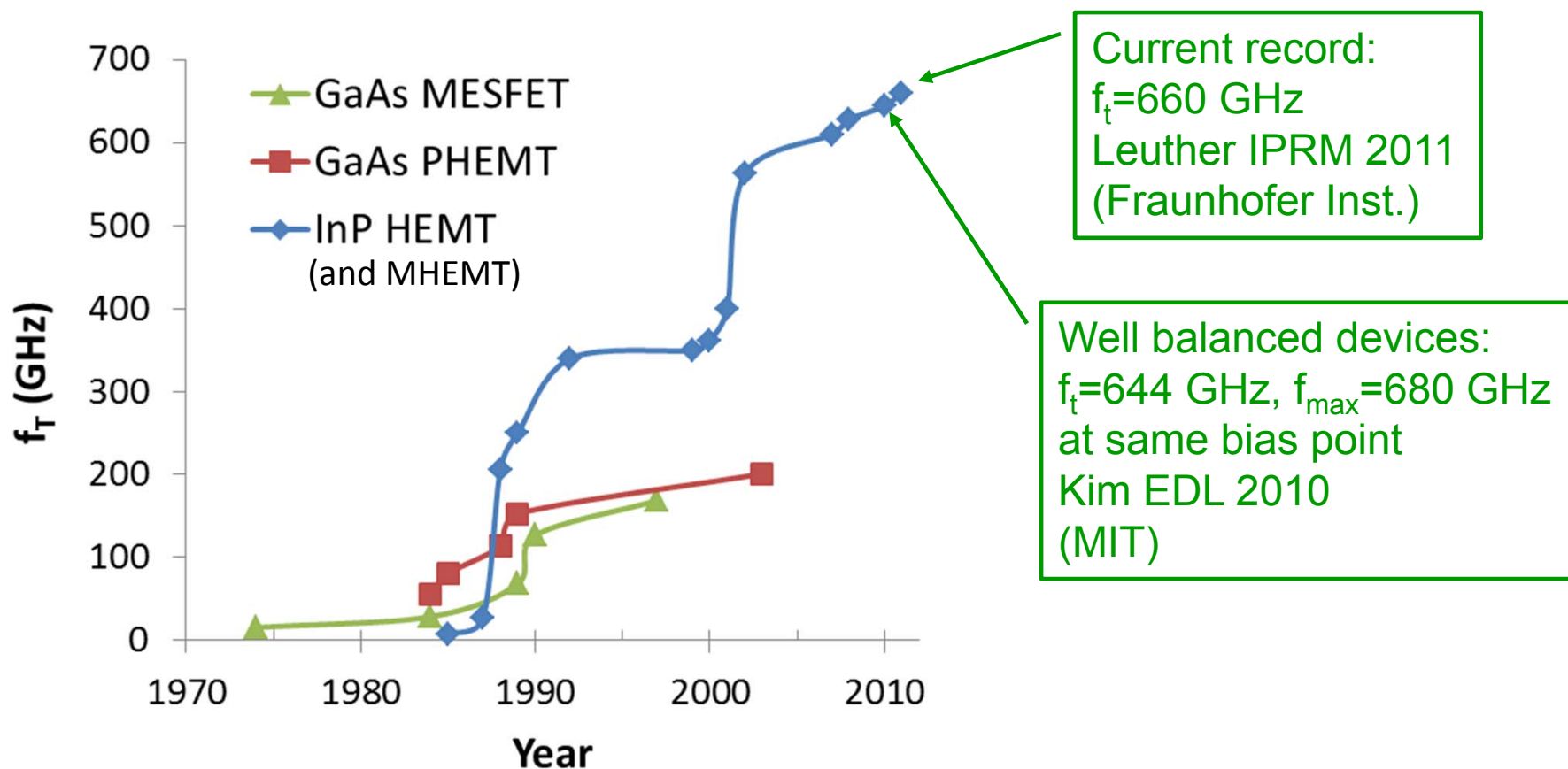
$f_T = 688$ GHz and $f_{\max} = 800$ GHz in

$L_g = 40$ nm $\text{In}_{0.7}\text{Ga}_{0.3}\text{As}$ MHEMTs

with $g_{m_max} > 2.7$ mS/ μm

D.-H. Kim, B. Brar and *J. A. del Alamo,
*Teledyne Scientific Company, *MIT*

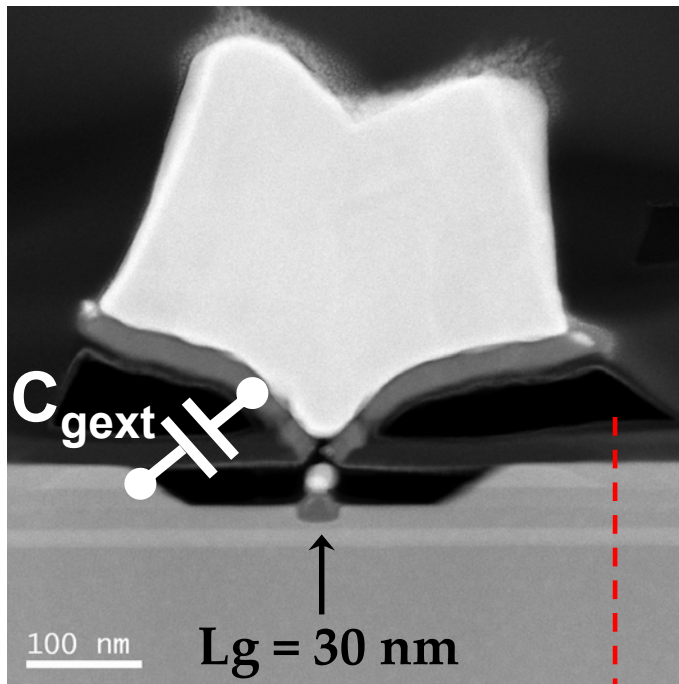
III-V HEMT: record f_T vs. time



For >20 years, record f_T obtained on InGaAs-channel HEMTs.
InGaAs-channel HEMTs offers record balanced f_T and f_{max} .

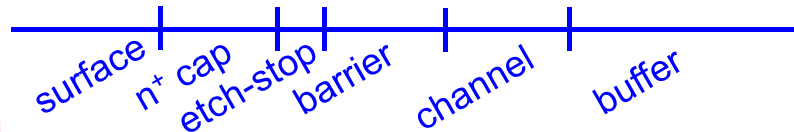
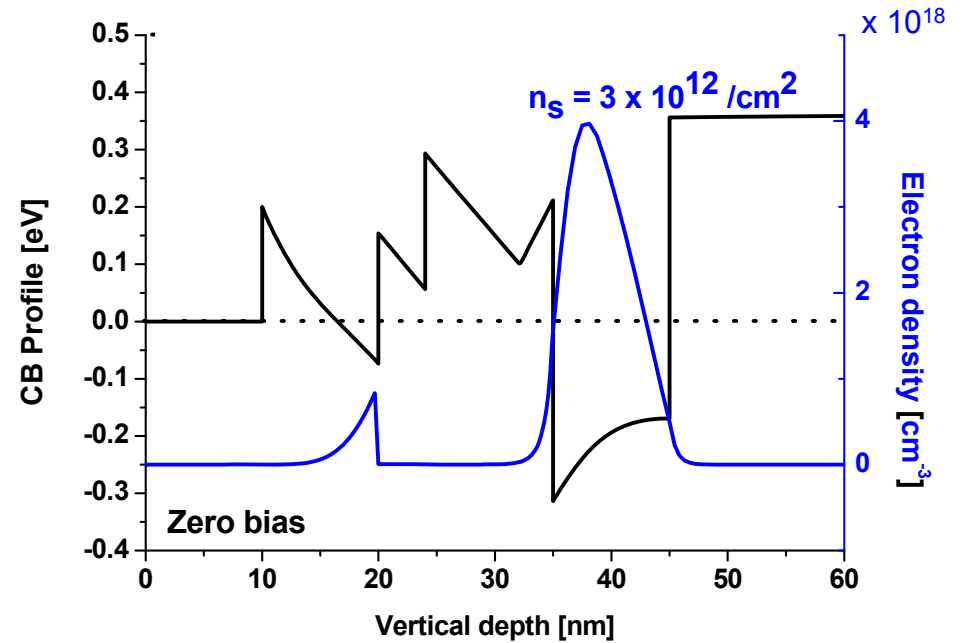
Strategy to improve f_T

- In typical HEMTs:
 - R_{ON} : 350 ~ 450 $\Omega\text{-}\mu\text{m}$
 - T-Gate: Stem height = ~ 150 nm



$R_{ON} \sim 420 \text{ Ohm-}\mu\text{m}$

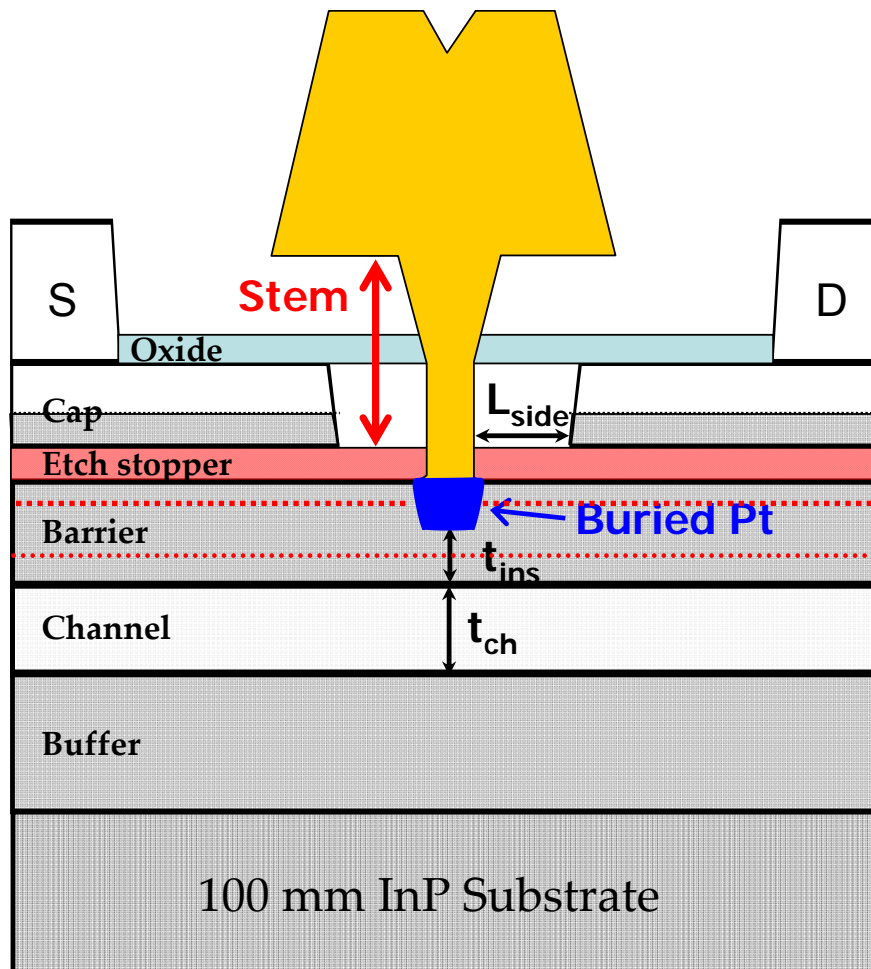
E_C and n in cross section



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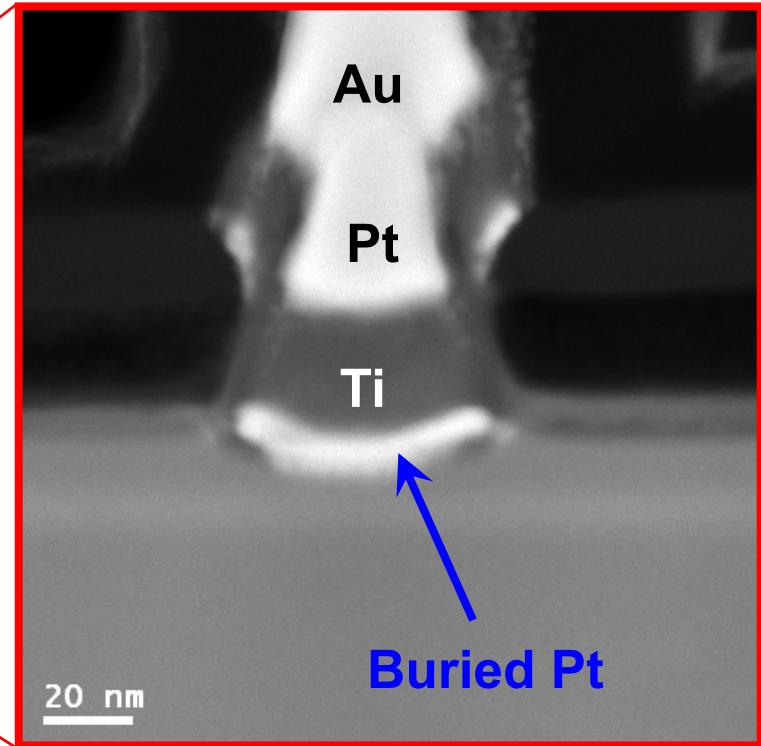
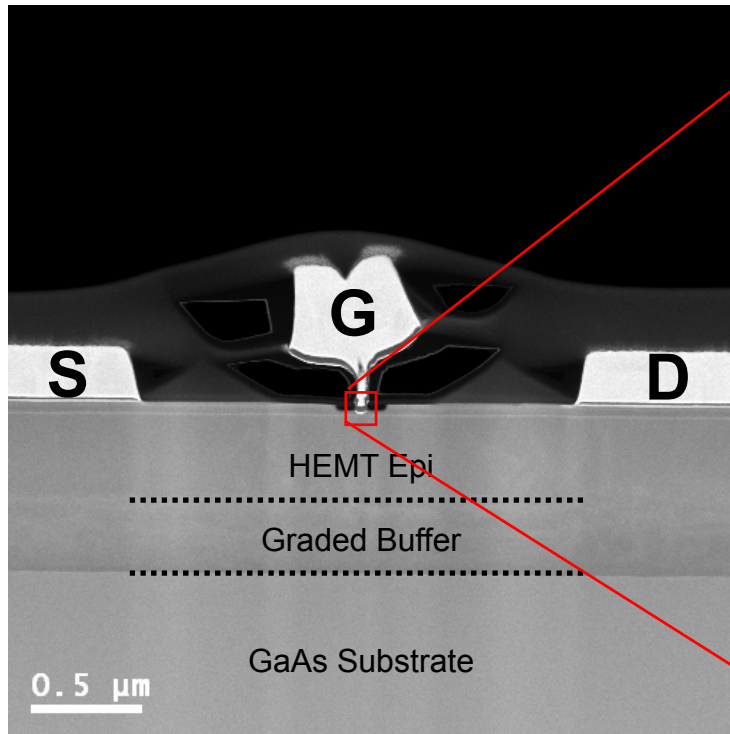
1. Introduction
2. Device Technology
3. DC and RF Characteristics
4. Analytical f_T Model
5. Conclusions

Device Technology



- SiO₂ assisted T-gate
 - $L_g = 40$ nm
 - **Gate-stem > 250 nm**
- Two-step recess (InP = 6 nm)
- **Pt (3 nm)/Ti/Pt/Au Schottky**
- QW: 10 nm In_{0.7}Ga_{0.3}As
 - $\mu_{n,Hall} > 10,000$ cm²/V-s
- *In_{0.52}Al_{0.48}As/**In_{0.7}Al_{0.3}As** spacer
- ****Dual Si δ -doping**

TEM Images

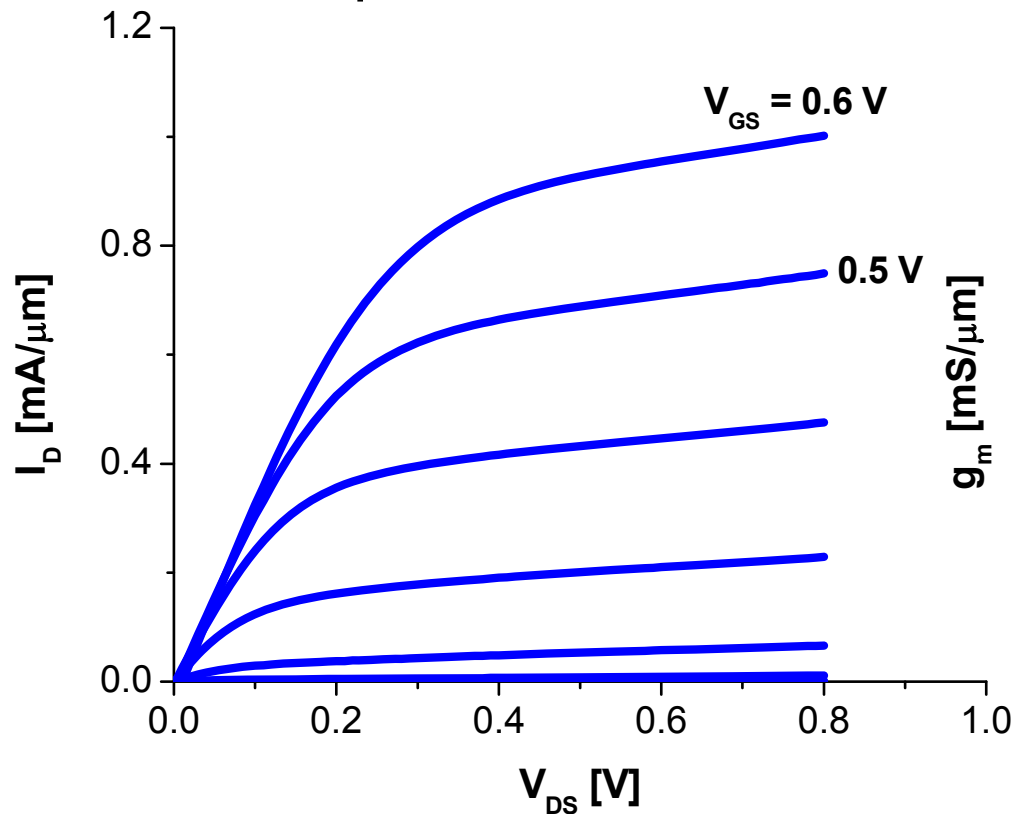


- Mo-based S/D with 2 μm
- Gate Stem > 250 nm

- $L_g = 40$ nm, $L_{side} = 100$ nm
- $t_{ins} = \sim 4$ nm

DC of $L_g = 40$ nm InGaAs MHEMTs

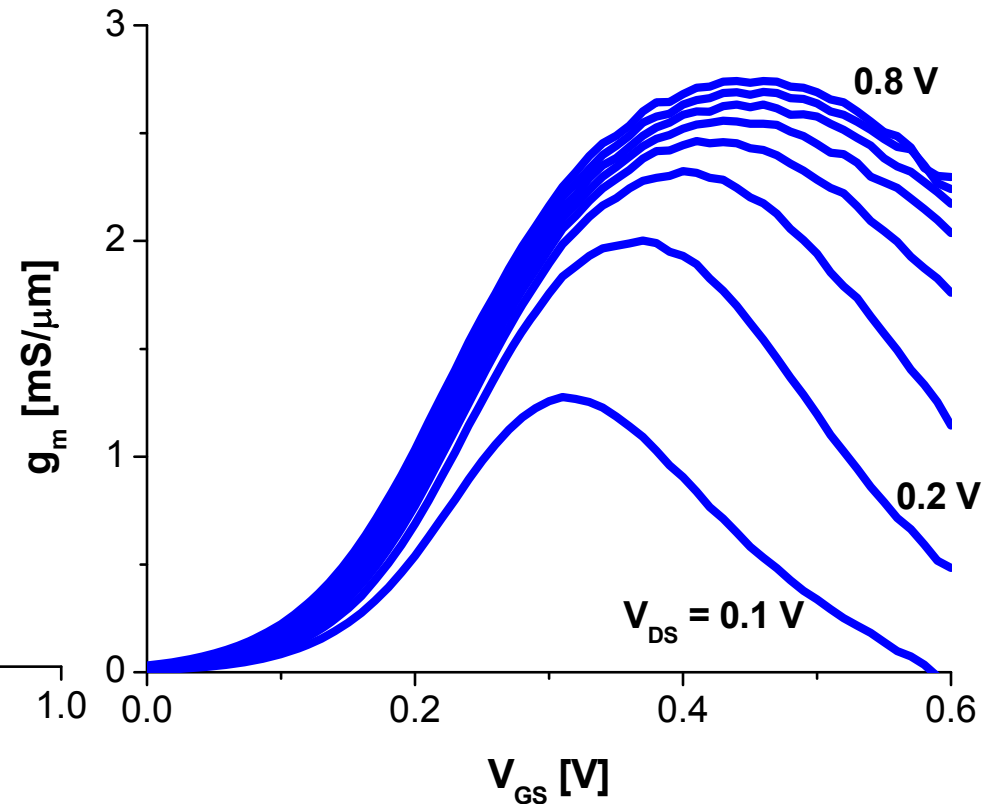
- Output characteristics -



- Maximum $I_D > 1$ mA/ μm

- $R_{ON} = 280 \Omega\text{-}\mu\text{m}$

- g_m characteristics -

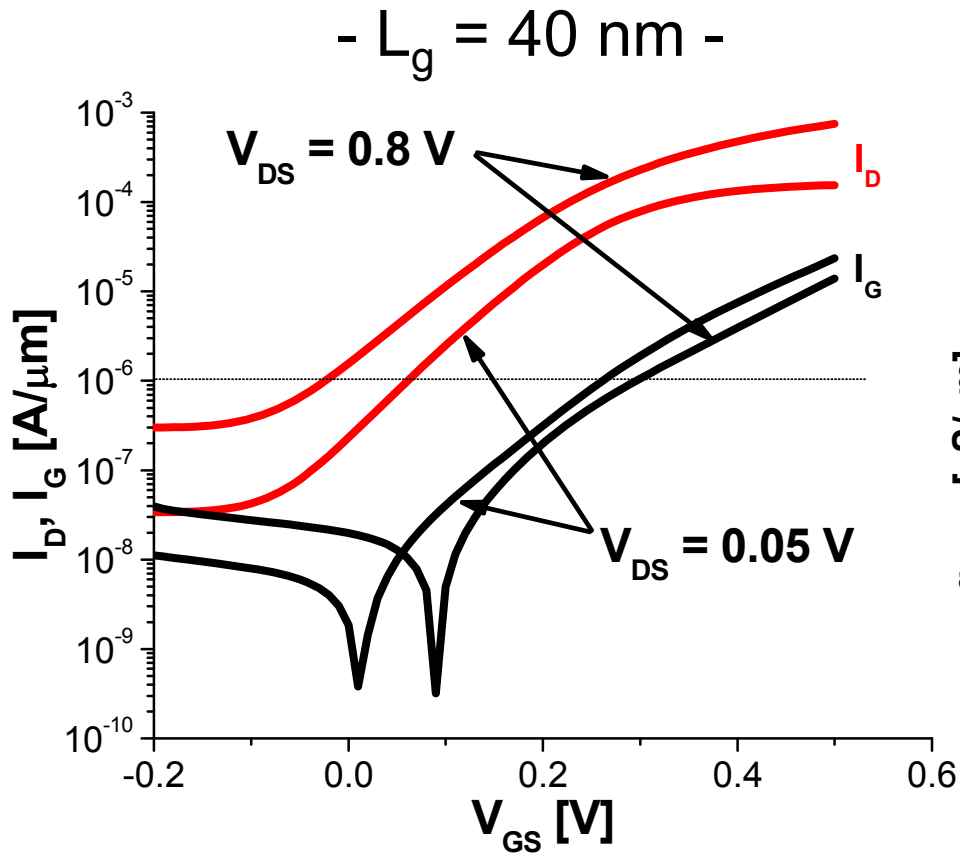


- $g_m > 2$ mS/ μm @ $V_{DS} = 0.3$ V

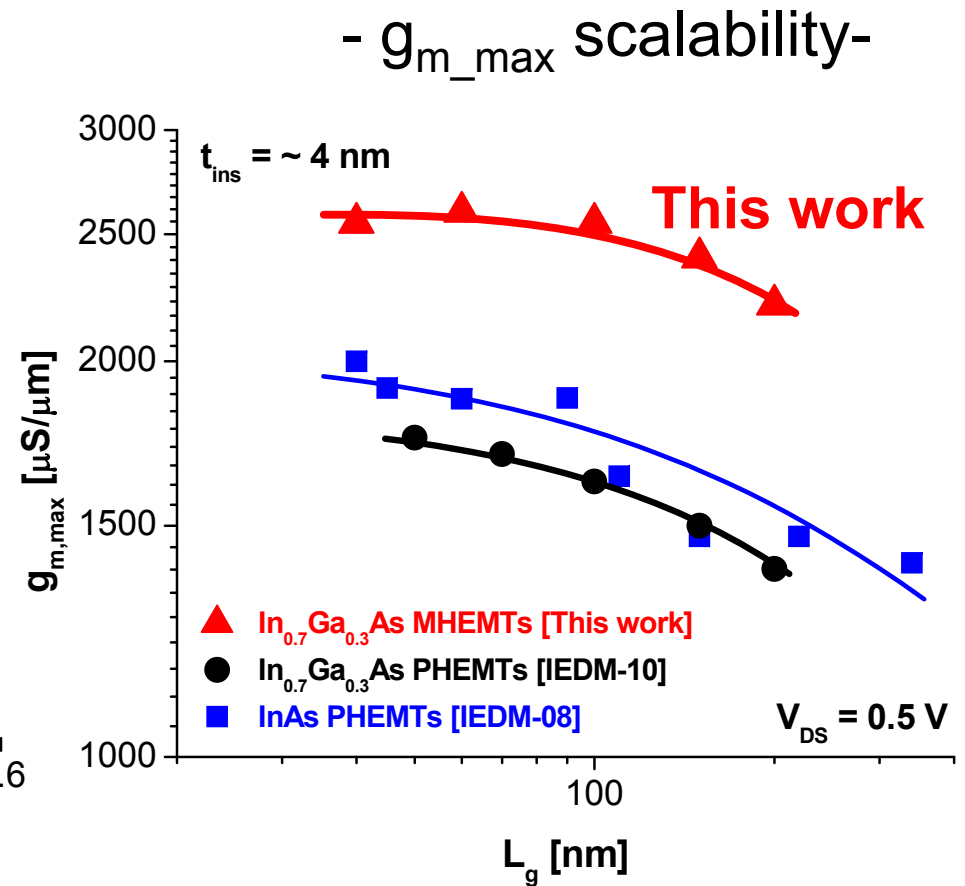
- $g_{m_max} = 2.75$ mS/ μm

@ $V_{DS} = 0.8$ V

Subthreshold characteristics



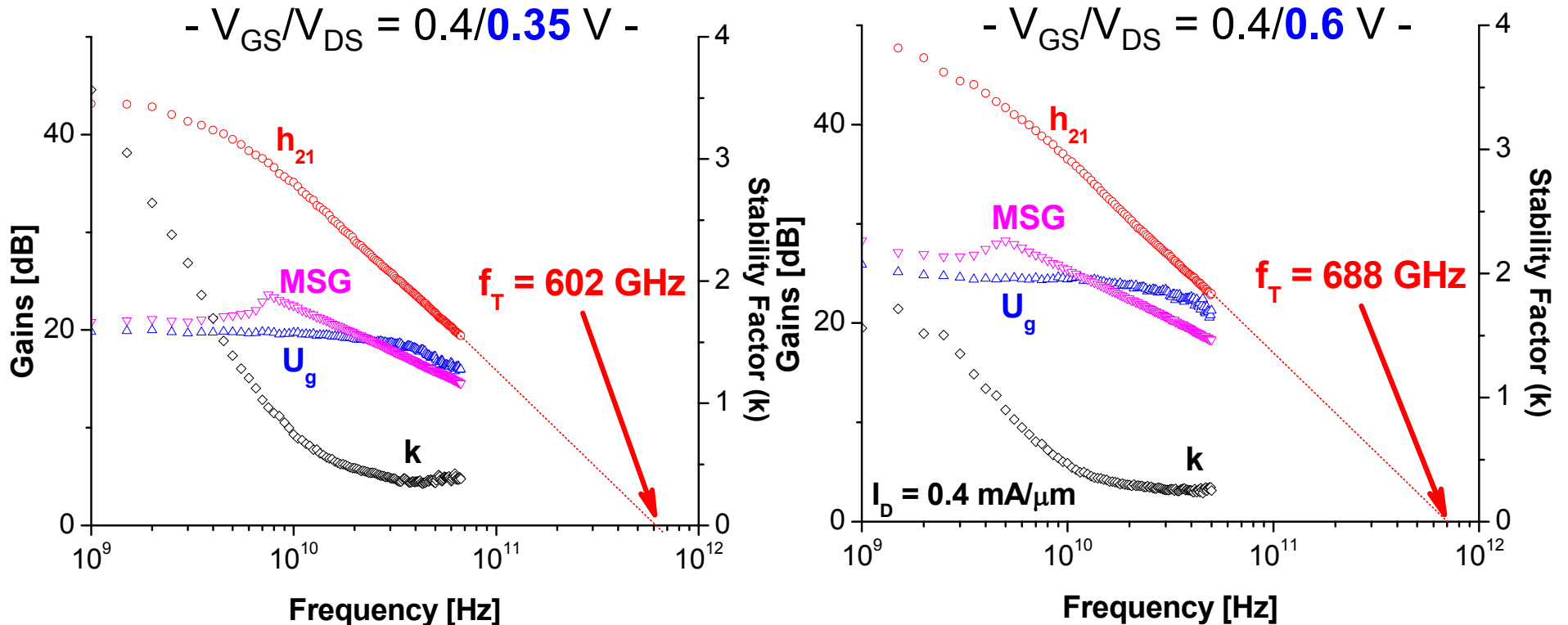
- $V_T = 0.02 \text{ V @ } V_{DS} = 0.5 \text{ V}$
- $S = 100 \text{ mV/dec.}, \text{ DIBL} = 105 \text{ mV/V}$



As $L_g \downarrow$,
 $\rightarrow g_m$ saturates.

f_T & f_{max} : $L_g = 40 \text{ nm}$, $W_g = 2 \times 20 \mu\text{m}$

Calibration: LRRM, De-embedding: OPEN/SHORT



- f_T already approaches to 600 GHz @ $V_{DS} = 0.35 \text{ V}$.
- **Record $f_T = 688 \text{ GHz}$ @ $V_{DS} = 0.6 \text{ V}$.**

Gummel technique for f_T extraction

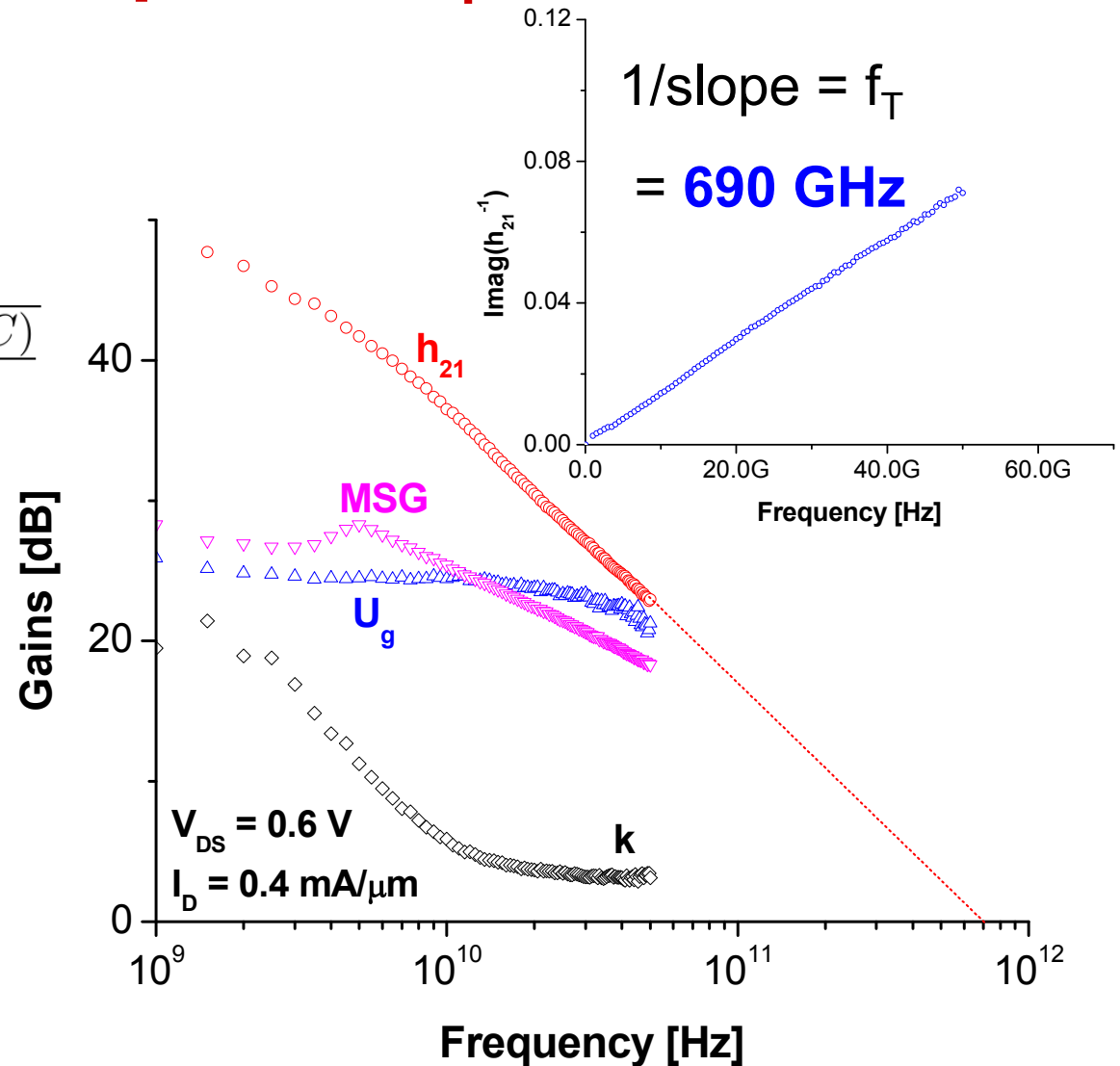
In one-pole system:

$$h_{21}(f) = \frac{h_{21}(DC)}{1 + jf \frac{h_{21}(DC)}{f_T}}$$

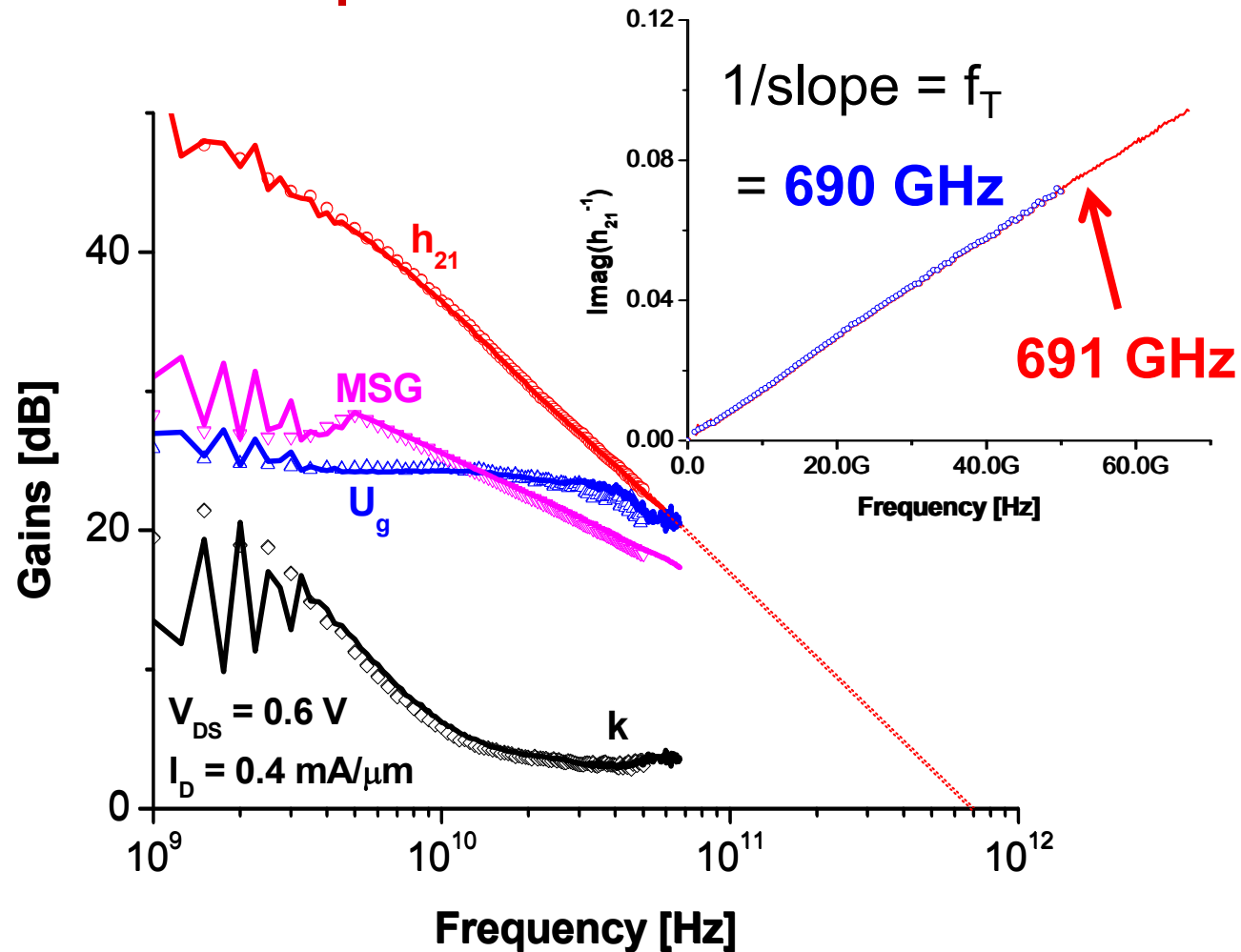
Then:

$$\text{Im}\left[\frac{1}{h_{21}(f)}\right] = \frac{f}{f_T}$$

Slope gives f_T

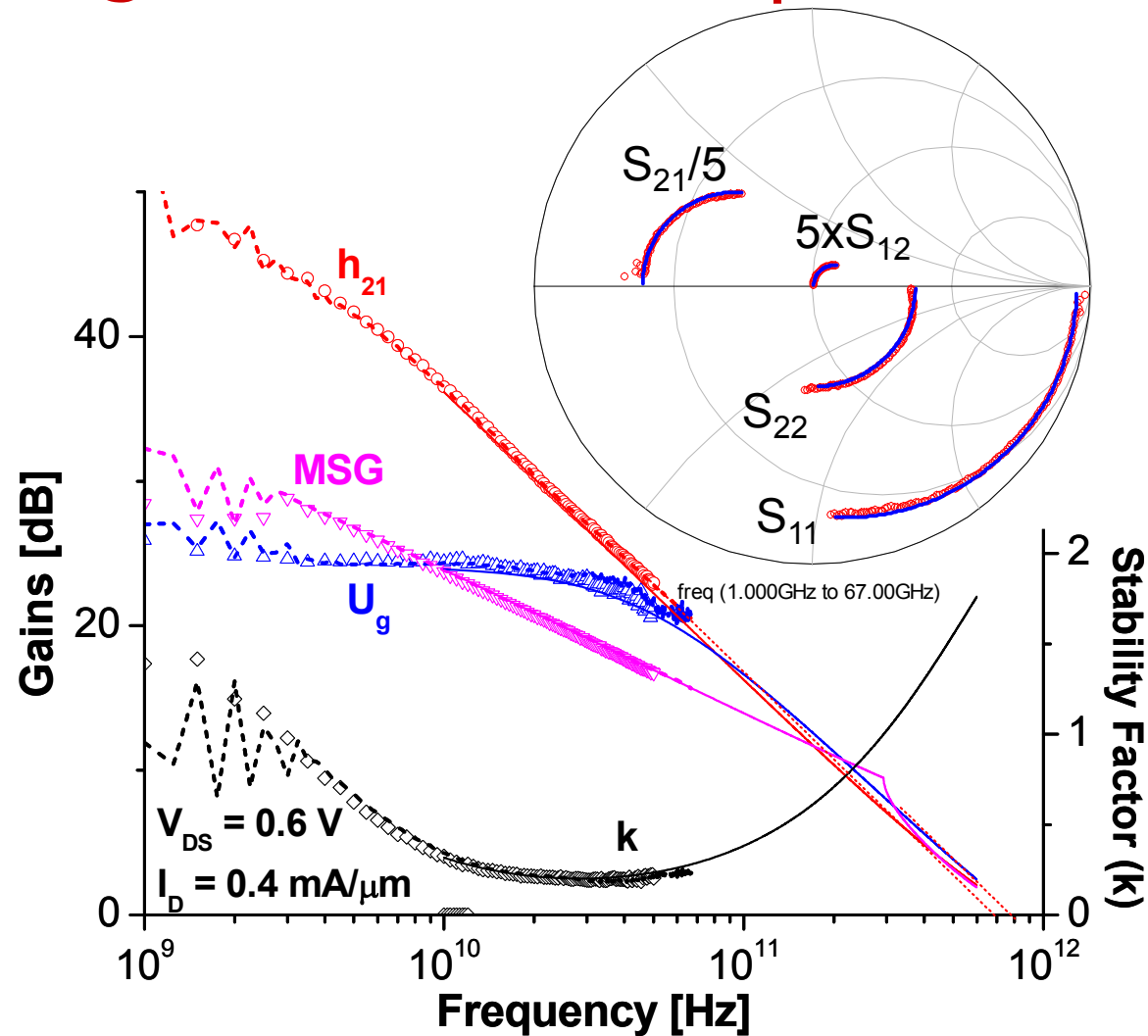


Different measurement system for f_T extraction



- 8510C @TSC: 1 ~ 50 GHz
- PNA @UCSB: 1 ~ 67 GHz

Small-signal model for f_T extraction



- Excellent agreement, modeled $f_T = 680$ GHz

$f_{max} = 800$ GHz

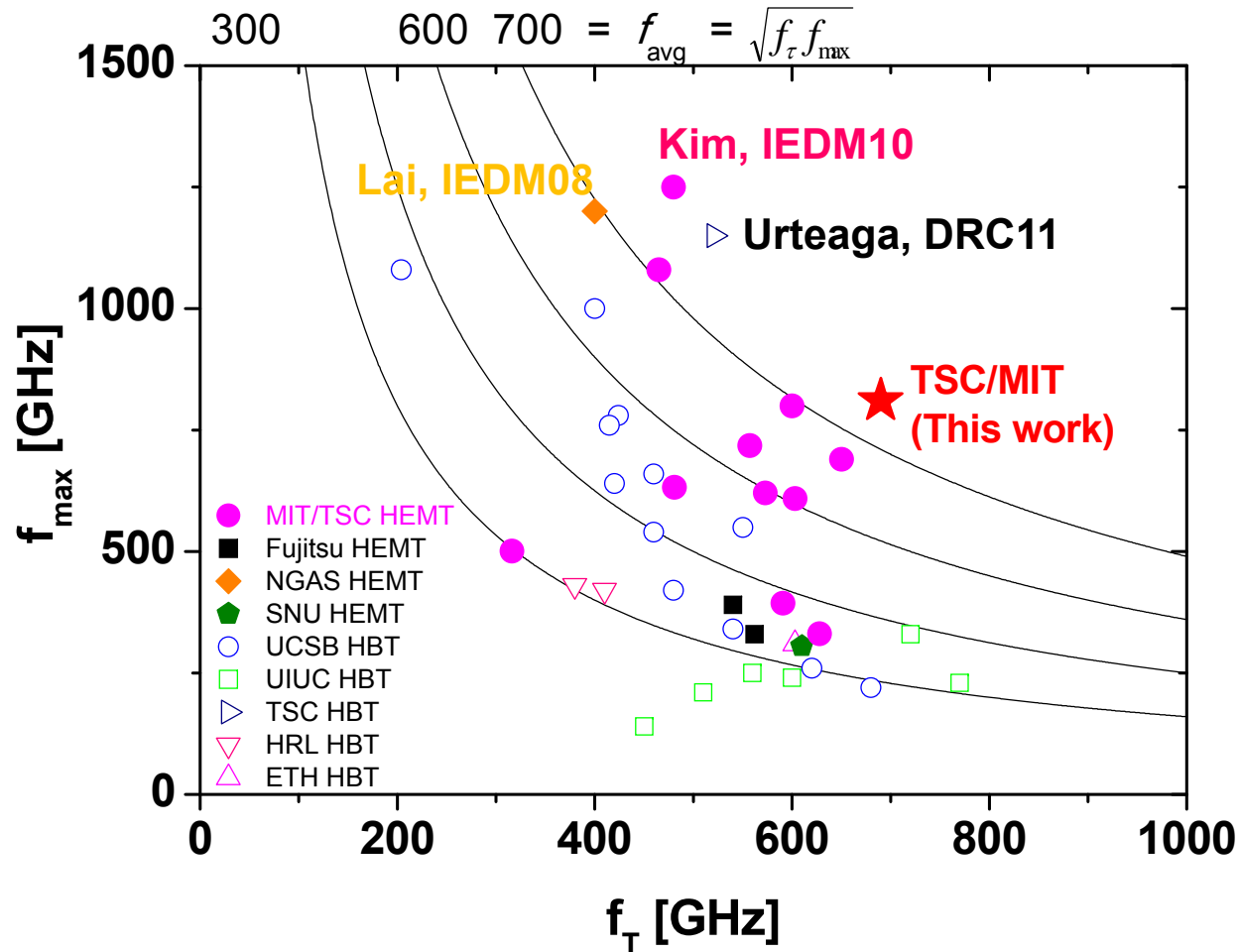
Summary on f_T measurements

Measurements in two different test benches:

		8510C @TSC	PNA @UCSB
f_T [GHz]	From H_{21}	688	688
	From Gummel's approach	690	691
	From Small-signal model	680	
f_{max} [GHz]		800	

All measurements at same bias point: $V_{GS}=0.4$ V, $V_{DS}=0.6$ V

Balance in f_T and f_{max}



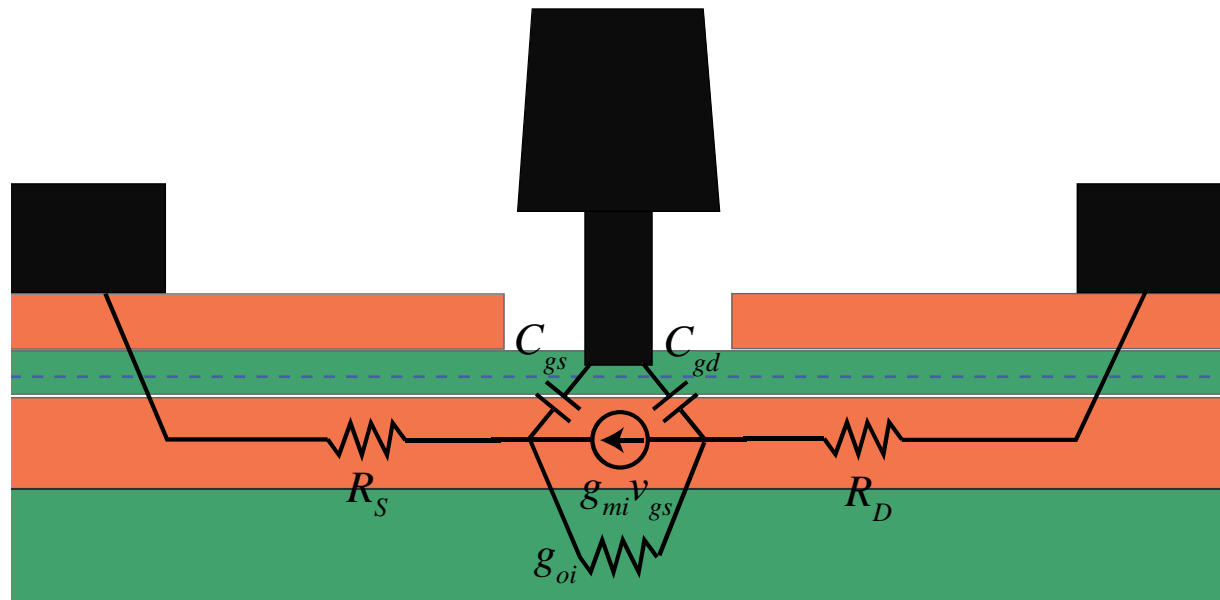
→ Record f_T FET

→ Best-balanced f_T and f_{max} transistor

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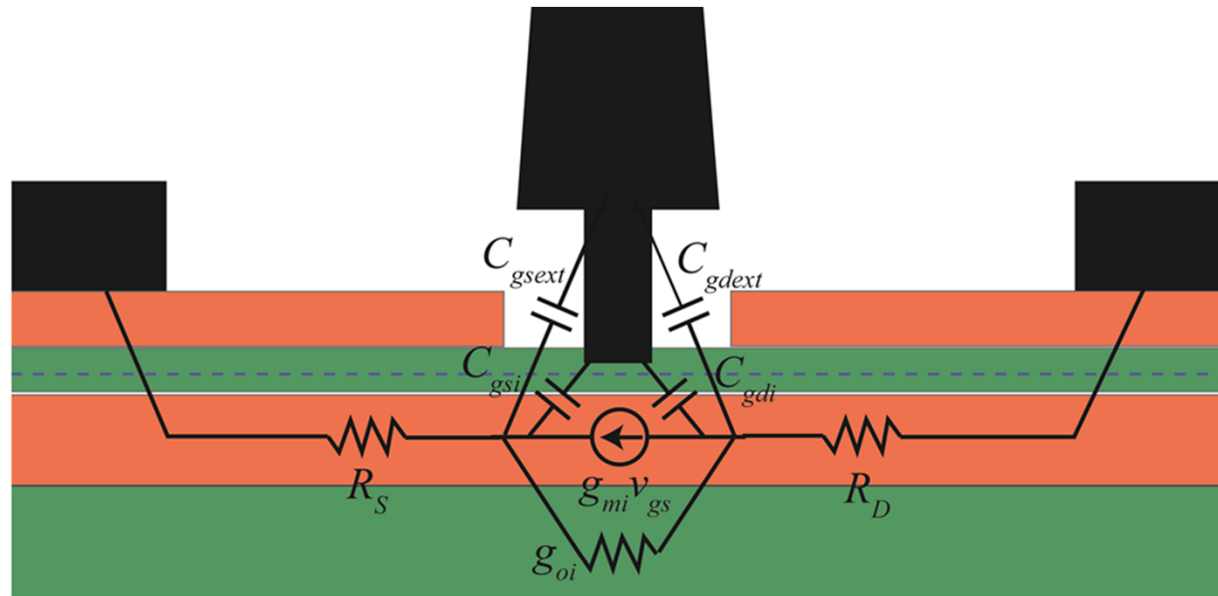
Analytical f_T Model



- First-order f_T expression for HEMT:

$$f_T = \frac{1}{2\pi} \frac{g_{mi}}{C_{gs} + C_{gd} + g_{mi}(R_S + R_D) \left[C_{gd} + (C_{gs} + C_{gd}) \frac{g_{oi}}{g_{mi}} \right]}$$

Break out 'extrinsic' capacitances



- Capacitance components [fF/mm]:

$$\begin{aligned}
 C_{gs} &= C_{gsi} + C_{gsext} \\
 &= C_{gsi_areal} \times L_g + C_{gsext} \\
 &\quad [fF/\mu m^2]
 \end{aligned}$$

$$\begin{aligned}
 C_{gd} &= C_{gdi} + C_{gdext} \\
 &= C_{gdi_areal} \times L_g + C_{gdext} \\
 &\quad [fF/\mu m^2]
 \end{aligned}$$

Delay time analysis

- Delay time:

$$\tau = \frac{1}{2\pi f_T} = \tau_t + \tau_{ext} + \tau_{par}$$

- Components of delay time:

$$\tau_t = \frac{C_{gsi} + C_{gdi}}{g_{mi}} = \frac{(C_{gsi_areal} + C_{gdi_areal}) L_g}{g_{mi}} = \frac{L_g}{v_e}$$

Intrinsic delay
(transit time)

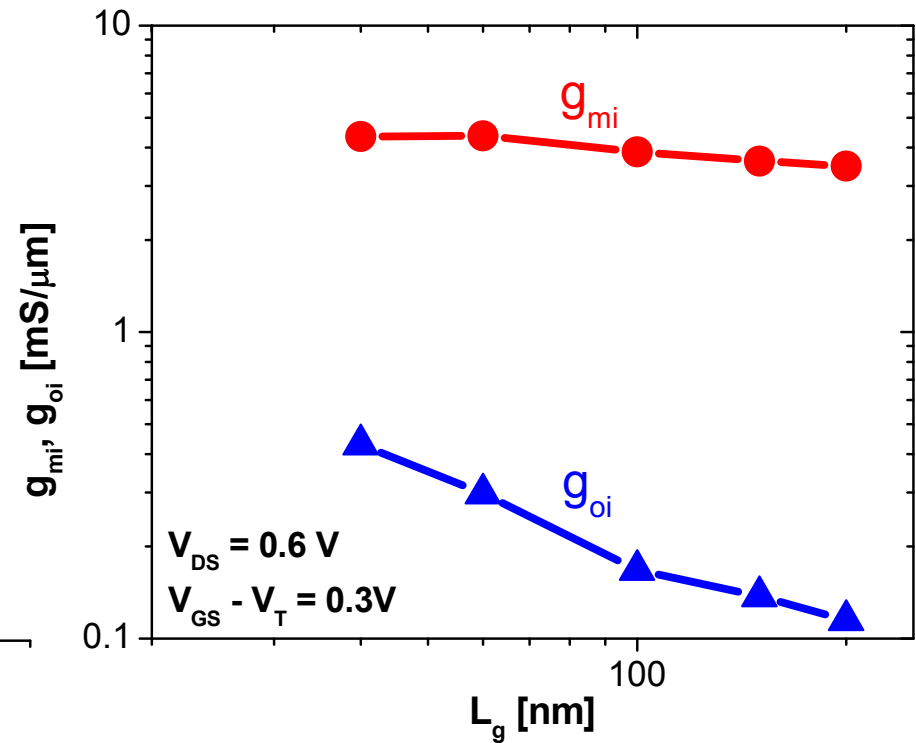
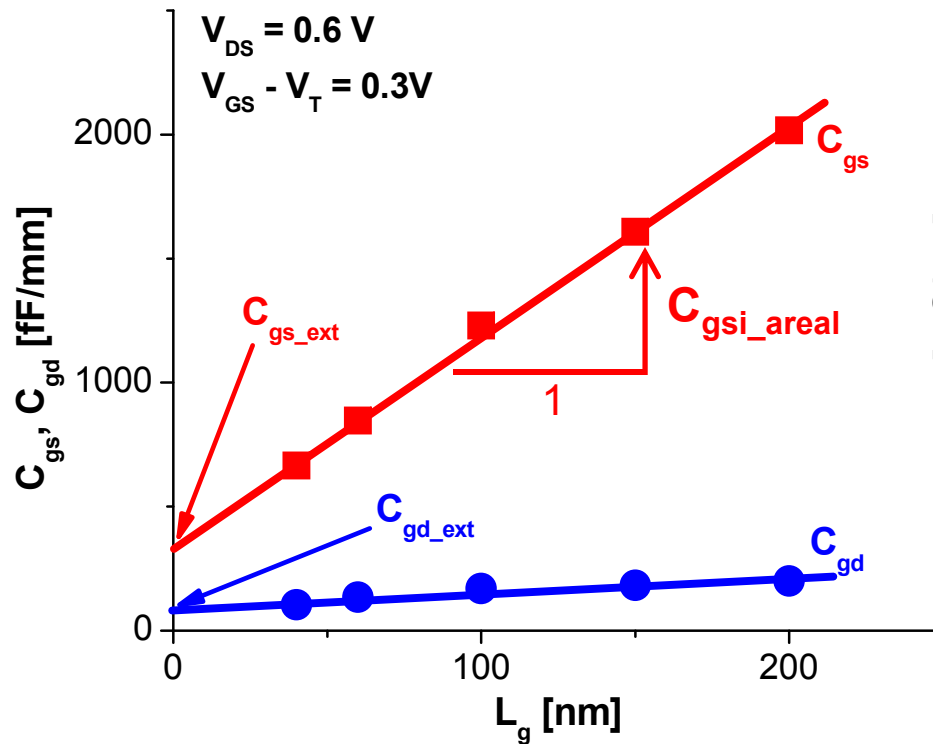
Extrinsic
delay

$$\tau_{ext} = \frac{C_{gsext} + C_{gdext}}{g_{mi}}$$

Parasitic
delay

$$\tau_{par} = (R_S + R_D) \left[C_{gd} + (C_{gs} + C_{gd}) \frac{g_{oi}}{g_{mi}} \right]$$

L_g -dependent model parameters



- Linearly proportional to L_g
- $C_{gs_ext} > C_{gd_ext}$
 $\leftarrow |V_{gs}| < |V_{gd}|$

As $L_g \downarrow$,

- g_{mi} saturates at $L_g = \sim 60 \text{ nm}$
- g_{oi} continues to increase

$\rightarrow g_{mi}/g_{oi} \downarrow$

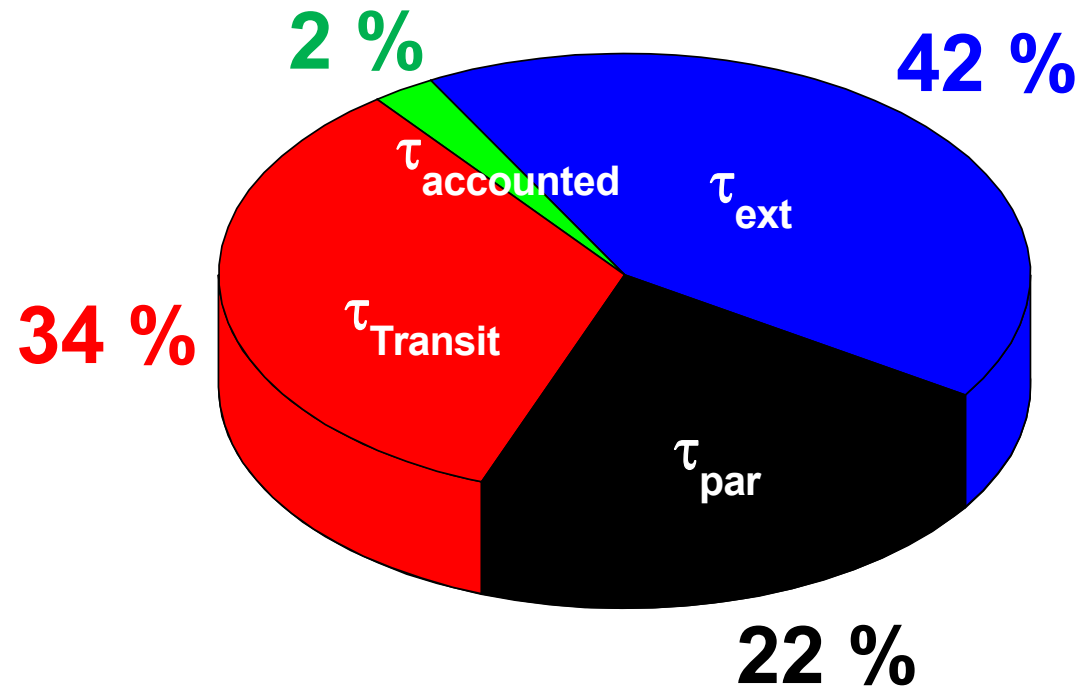
Delay components of $L_g=40$ nm InGaAs MHEMT

Delay time from f_t : ~231 fs

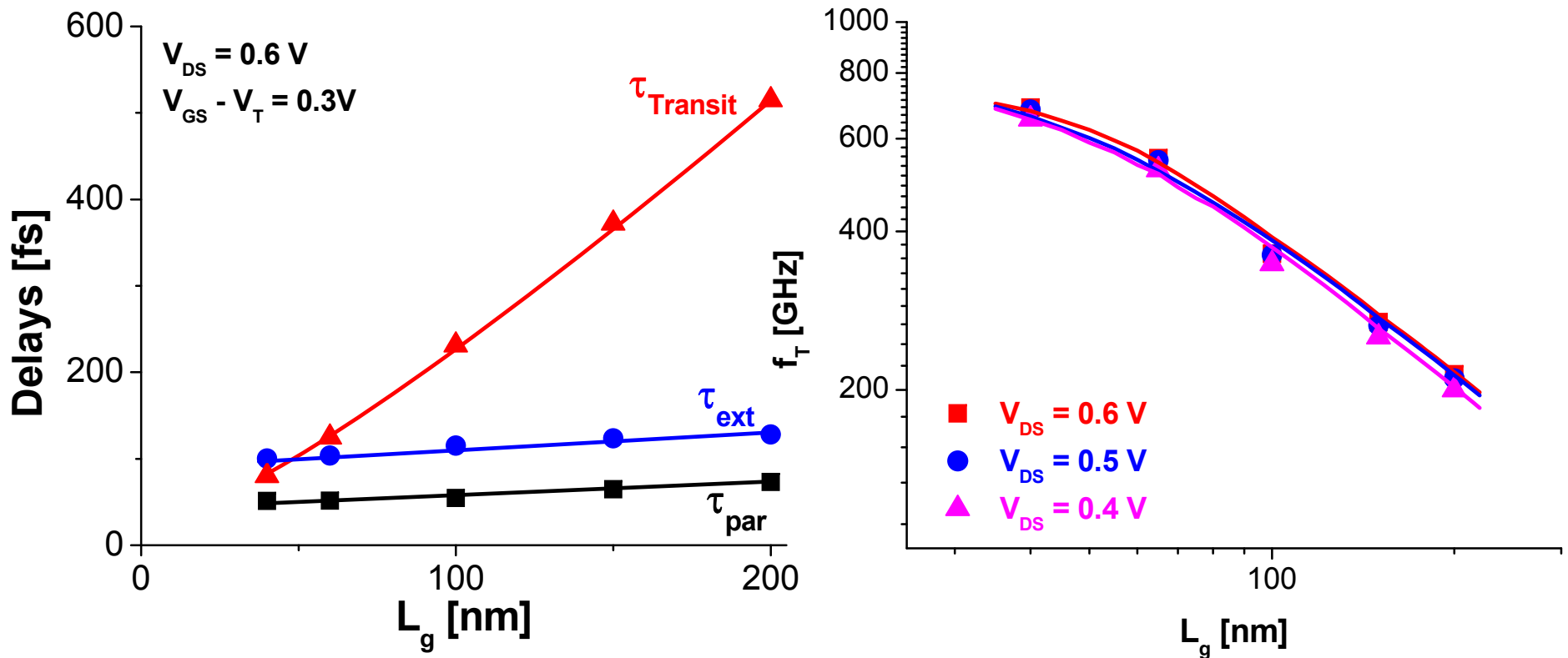
- Intrinsic delay: ~81 fs
- Extrinsic delay: ~ 99 fs
- Parasitic delay: ~50 fs
- Unaccounted: ~9 fs

least significant,
yields $v_e=5 \times 10^7$ cm/s

most significant



Scaling of delay components



τ_{ext} and τ_{par} do not scale, become dominant for $L_g < \sim 60\text{ nm}$.

Options to improve f_T

- Intrinsic delay:

$$\tau_t = \frac{C_{gsi} + C_{gdi}}{g_{mi}} = \frac{L_g}{v_e}$$

$L_g \downarrow$ (without degrading g_{mi}), $v_e \uparrow \rightarrow$ channel engineering

- Extrinsic delay:

$$\tau_{ext} = \frac{C_{gsext} + C_{gdext}}{g_{mi}}$$

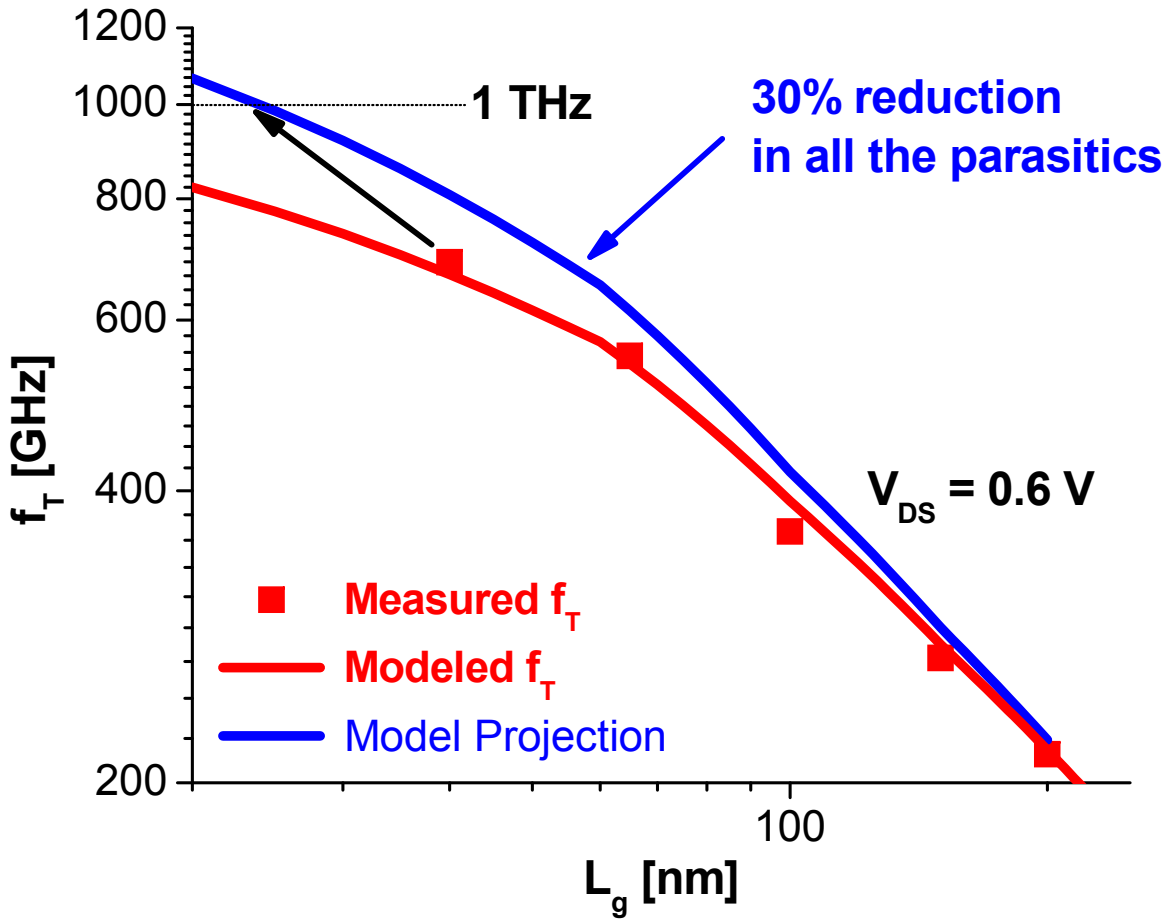
C_{gsext} , $C_{gdext} \downarrow$, or alternatively $g_{mi} \uparrow$ (harmonious scaling)

- Parasitic delay:

$$\tau_{par} = (R_S + R_D) \left[C_{gd} + (C_{gs} + C_{gd}) \frac{g_{oi}}{g_{mi}} \right]$$

$R_S + R_D \downarrow$, increase electrostatic integrity: $g_{oi}/g_{mi} \downarrow$

Model Projection



$f_T = 1 \text{ THz}$ is *feasible* at $L_g = \sim 25 \text{ nm}$.

Summary

40-nm $\text{In}_{0.7}\text{Ga}_{0.3}\text{As}$ MHEMTs on GaAs substrate

- $R_{\text{ON}} = 280 \text{ } \Omega\text{-}\mu\text{m}$, $g_{\text{m_max}} > 2.7 \text{ mS}/\mu\text{m}$ @ $V_{\text{DS}} = 0.8 \text{ V}$
- $S = 100 \text{ mV/dec.}$, $\text{DIBL} = 105 \text{ mV/V}$
- Measured $f_{\text{T}} = 688 \text{ GHz}$ (**Record** in any FET)
- $f_{\text{T}}/f_{\text{max}} = 688/800 \text{ GHz}$ (**Best-balanced** transistor)

Analytical f_{T} Model

- Excellent description of f_{T} behavior in III-V HEMTs
- Guidance to improve f_{T} beyond 1 THz